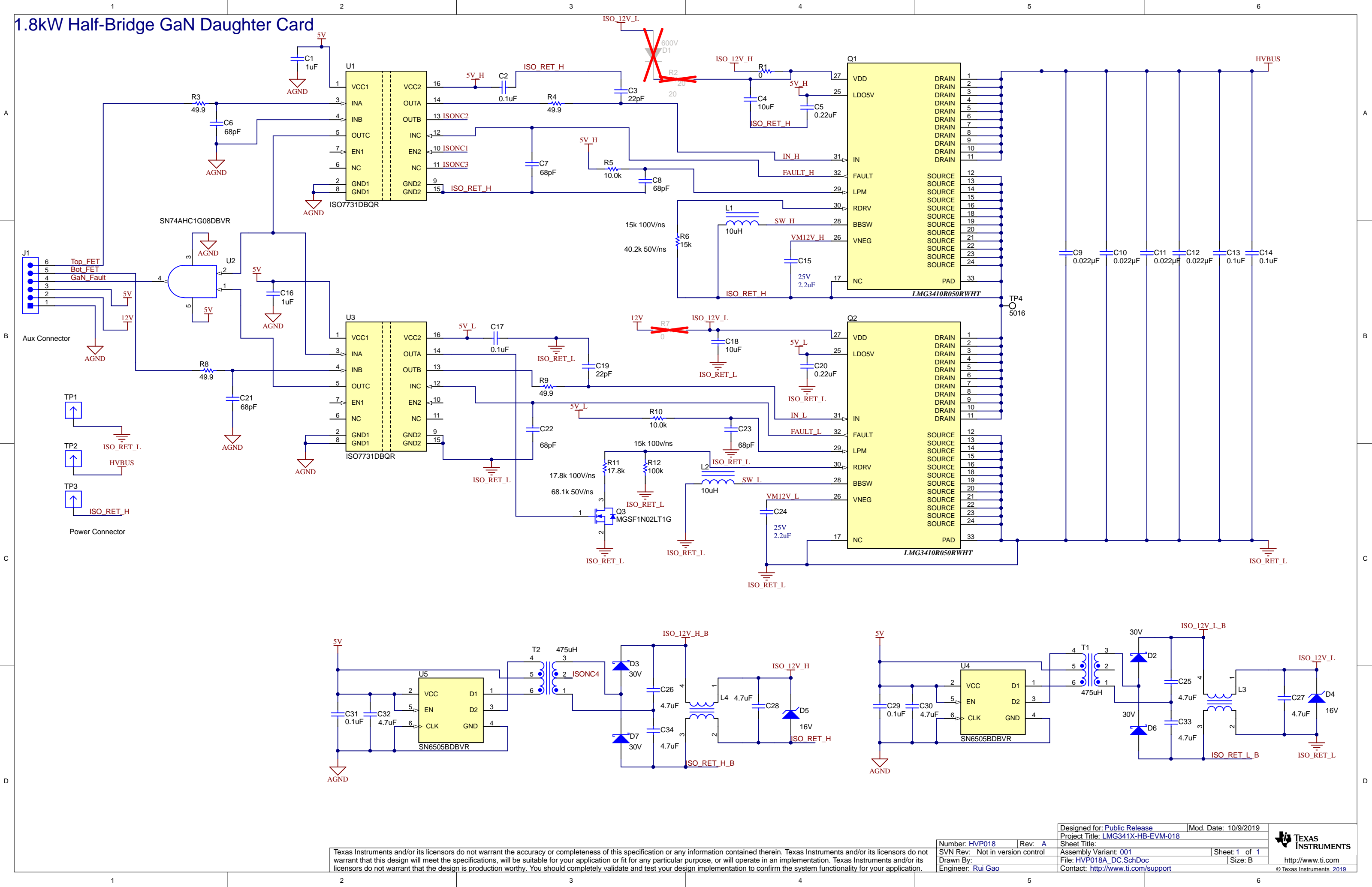


# 1.8kW Half-Bridge GaN Daughter Card



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Number: HVP018  
Rev: A  
SVN Rev: Not in version control  
Drawn By:  
Engineer: Rui Gao

Designed for: Public Release  
Project Title: LMG341X-HB-EVM-018  
Sheet Title:  
Assembly Variant: 001  
File: HVP018A\_DC.SchDoc  
Contact: <http://www.ti.com/support>

Mod. Date: 10/9/2019  
Sheet: 1 of 1  
Size: B  
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PCB Number: HVP018

PCB Rev: A

LBL1

PCB Label

THT-14-423-10

Size: 0.65" x 0.20 "



CAUTION HOT SURFACE



DANGER HIGH VOLTAGE



CAUTION HOT SURFACE



DANGER HIGH VOLTAGE

Variant/Label Table	
Variant	Label Text
001	LMG3410EVM-018
002	LMG3411EVM-018

PCB  
LOGO

Texas Instruments



CE Mark

PCB  
LOGO

FCC disclaimer

PCB  
LOGO

WEEE logo

ZZ2

Assembly Note

These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3

Assembly Note

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

H2

MECH

Mechanical spring

H3

MECH

Mechanical push pin. PIP3.175x13.2

H4

MECH

Thermal Interface Material

H5

MECH

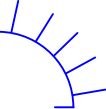
Mechanical spring

H6

MECH

Mechanical push pin. PIP3.175x13.2

H1

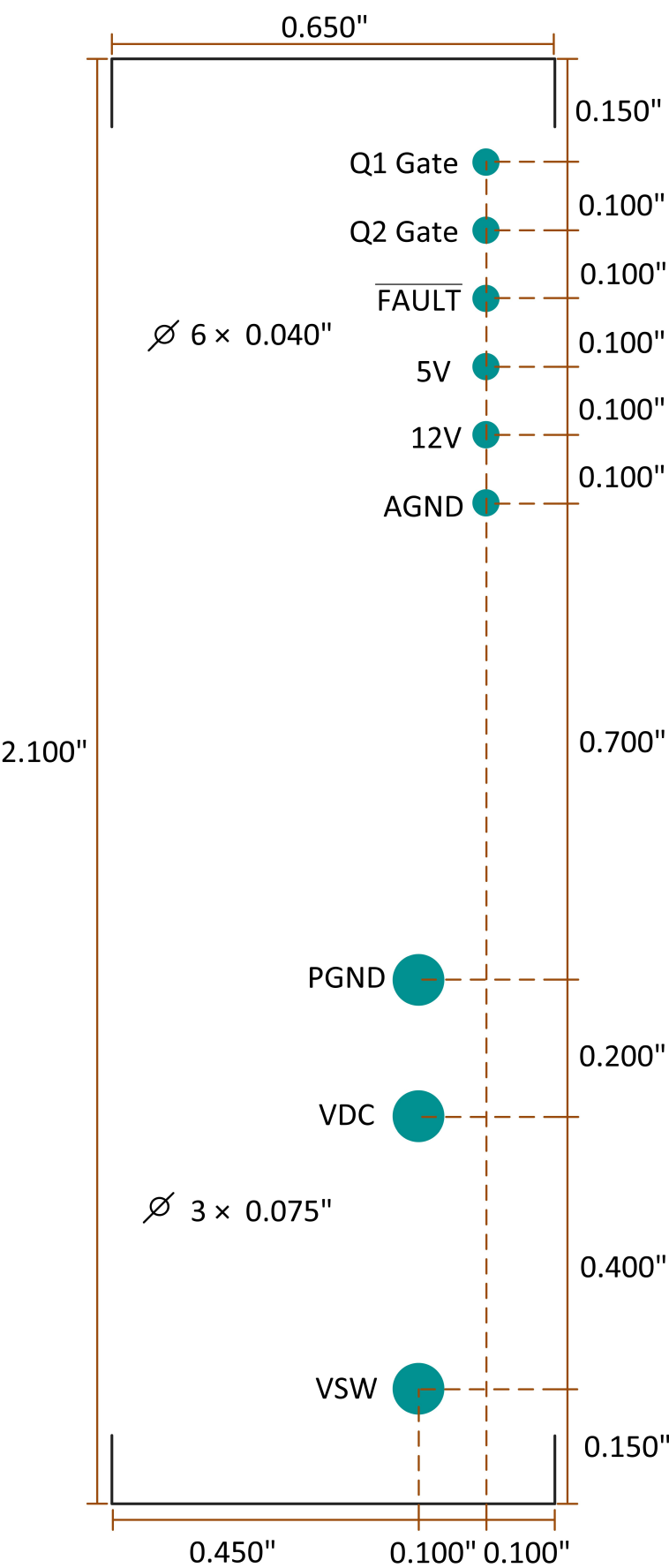


UBM30-20BP-0N04

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Orderable: LMG3410EVM-018		Designed for: Public Release		Mod. Date: 5/30/2019
TID #: N/A		Project Title: LMG341X-HB-EVM-018		
Number: HVP018		Rev: A	Sheet Title:	
SVN Rev: Not in version control		Assembly Variant: 001		Sheet: 2 of 3
Drawn By:		File: HVP018A_Hardware.SchDoc		Size: B
Engineer: Rui Gao		Contact: http://www.ti.com/support		

TI LMG3410 FET Card Recommended Footprint



Recommended Signal Connector: Molex 0448120024

Recommended Heatsink Set  
TIM: HF-300P  
Heatsink: Alpha Novatech UBM30-20BP

Recommended Power Connector: Mill-Max 0312-0-15-XX-34-XX-10-0

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